

N-Ch MOSFET

General Description

The WST2088 is the highest performance trench N-ch MOSFETs with extreme high cell density, which provide excellent RDSON and gate charge for most of the small power switching and load switch applications.

The WST2088 meet the RoHS and Green Product requirement with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

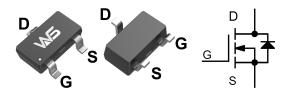
Product Summery

| BVDSS | RDSON | ID |
|-------|-------|------|
| 20V | 8mΩ | 8.8A |

Applications

- Power switching application
- Hard Switched and High Frequency Circuits
- Uninterruptible Power Supply

SOT-23-3L Pin Configuration



Absolute Maximum Ratings

| Symbol | Parameter | Rating | Units | |
|--------------------------------------|--|------------|------------|--|
| V_{DS} | Drain-Source Voltage | 20 | V | |
| V_{GS} | Gate-Source Voltage | ±12 | V | |
| I _D @T _c =25℃ | Continuous Drain Current, V _{GS} @ 4.5V | 8.8 | Α | |
| I _D @T _c =70℃ | Continuous Drain Current, V _{GS} @ 4.5V | 6.2 | А | |
| I _{DP} | Pulsed Drain Current | 40 | Α | |
| P _D @T _A =25°C | Total Power Dissipation | 1.5 | W | |
| T _{STG} | Storage Temperature Range | -55 to 150 | $^{\circ}$ | |
| TJ | Operating Junction Temperature Range | -55 to 150 | $^{\circ}$ | |

Thermal Data

| Symbol | Parameter | Тур. | Max. | Unit |
|--------|--|------|------|------|
| Rthj-a | Maximum Thermal Resistance, Junction-ambient | | 25 | °C/W |
| Rthj-c | Maximum Thermal Resistance, Junction-case | | 8 | °C/W |



Electrical Characteristics (T_J=25 C, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Unit |
|--------------------------------------|--|---|------|-------|------|------|
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V , I _D =250uA | 20 | | | V |
| $\triangle BV_{DSS}/\triangle T_{J}$ | BVDSS Temperature Coefficient | Reference to 25°C , I _D =1mA | | 0.018 | | V/°C |
| R _{DS(ON)} | Static Drain-Source On-Resistance ² | V _{GS} =4.5V , I _D =6A | | 8 | 13 | mΩ |
| | | V _{GS} =2.5V , I _D =5A | | 10 | 19 | |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{GS}=V_{DS}$, $I_D=250uA$ | 0.5 | | 1.3 | ٧ |
| I _{DSS} | Drain-Source Leakage Current | V _{DS} =16V , V _{GS} =0V. | | | 10 | uA |
| I _{GSS} | Gate-Source Leakage Current | V_{GS} = $\pm 12V$, V_{DS} = $0V$ | | | ±100 | nA |
| Qg | Total Gate Charge | | | 16 | | |
| Q_{gs} | Gate-Source Charge | V_{DS} =15V , V_{GS} =4.5V , I_{D} =6A | | 3 | | nC |
| Q_{gd} | Gate-Drain Charge | | | 4.5 | | |
| $T_{d(on)}$ | Turn-On Delay Time | | | 10 | | |
| Tr | Rise Time | V _{DS} =10V , V _{GS} =4.5V , | | 13 | | ns |
| $T_{d(off)}$ | Turn-Off Delay Time | $R_G=3.3\Omega$ $I_D=1A$ | | 28 | | 115 |
| T _f | Fall Time | | | 7 | | |
| C _{iss} | Input Capacitance | | | 1400 | | |
| Coss | Output Capacitance | V _{DS} =15V , V _{GS} =0V , f=1MHz | | 170 | | pF |
| C _{rss} | Reverse Transfer Capacitance | | | 135 | | |

Diode Characteristics

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Unit |
|-----------------|-------------------------|--|------|------|------|------|
| V _{SD} | Diode Forward Voltage | V _{GS} =0V , I _S =1A | | | 1.2 | V |
| t _{rr} | Reverse Recovery Time | IF=1A , V _{GS} =0V, | | 8.5 | | nS |
| Qrr | Reverse Recovery Charge | dl/dt=100A/µs | | 2.5 | | nC |

Notes:

1. Pulse width limited by Max. junction temperature.

2.Pulse test

3.Surface mounted on 1 in 2 copper pad of FR4 board, t \leq 10sec; 60 °C/W at steady state.

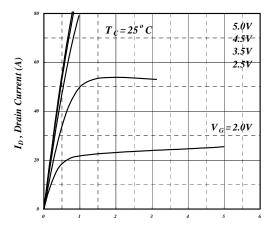
4.Starting $T_j{=}25^{\circ}C$, $V_{DD}{=}20V$, L=0.1mH , $R_G{=}25\Omega,\,V_{GS}{=}10V$

5.0V

 $T_{\epsilon} = 150^{\circ} C$



Typical Characteristics



 $V_{G} = 2.0V$

Fig 1. Typical Output Characteristics

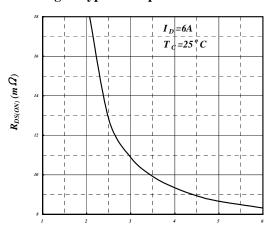


Fig 2. Typical Output Characteristics

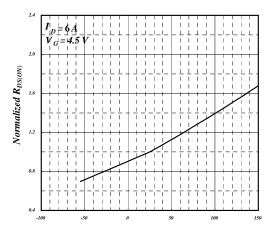


Fig 3. On-Resistance v.s. Gate Voltage

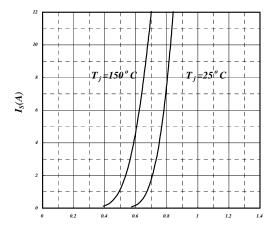


Fig 4. Normalized On-Resistance v.s. Junction Temperature

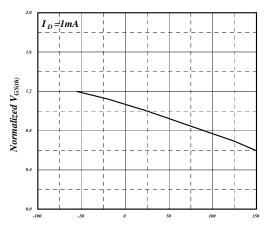


Fig 5. Forward Characteristic of Reverse Diode

Fig 6. Gate Threshold Voltage v.s.
Junction Temperature



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f=1.0MHz

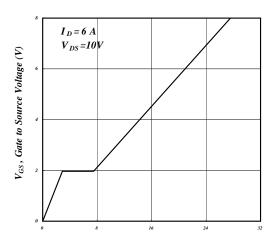


Fig 7. Gate Charge Characteristics

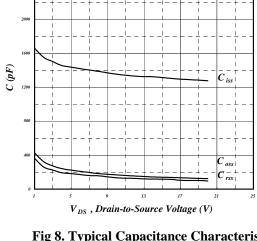


Fig 8. Typical Capacitance Characteristics

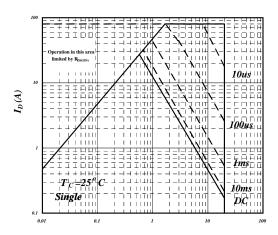


Fig 9. Maximum Safe Operating Area

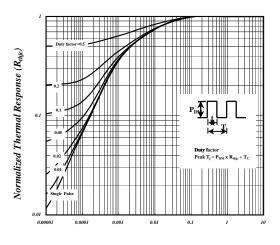


Fig 10. Effective Transient Thermal Impedance

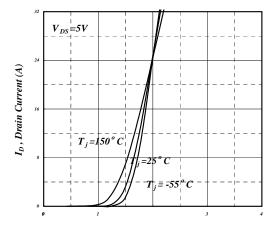


Fig 11. Transfer Characteristics

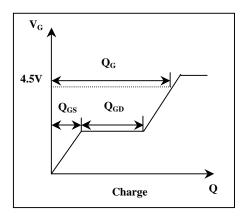
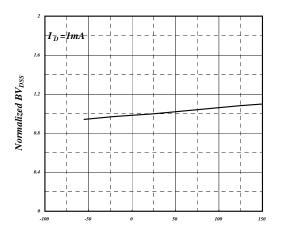
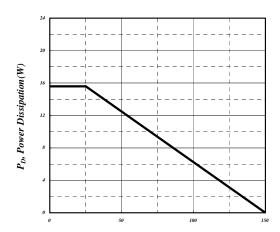


Fig 12. Gate Charge Waveform







 $\label{eq:posterior} \textbf{Fig 13. Normalized BV}_{DSS} \ \ \textbf{v.s. Junction} \\ \textbf{Temperature}$

Fig 14. Total Power Dissipation

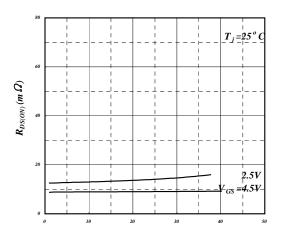


Fig 15. Typ. Drain-Source on State Resistance



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